



7-9 September Genova-Italy

6th International Conference on System-Integrated Intelligence

Intelligent, flexible and connected systems in products and production

CALL FOR PAPERS

ABOUT SYSINT

SysInt is an international conference about system-integrated intelligence. held biannually. The conference provides a forum for academia and industry to disseminate their latest innovations and

practices in field of system-integrated intelligence.

The goal is to present recent and exciting results on the integration of new, intelligent functionalities into materials, components, systems and products.

The conference addresses industry and society needs. requirements and expectations.

Remote participation will be possible

SCIENTIFIC TRACKS and SPECIAL SESSIONS

Scientific Tracks:

- Artificial Intelligence
- Pervasive and Ubiquitous Intelligence
- Sensors and Sensing Systems
- Smart Factory and Logistic Systems
- Structural Health Monitoring
- Soft Robotics
- Human Machine Interaction
- Cognitive Systems

Special Sessions:

- 1: Applications and Challenges in the use of 5G in Production and Logistics
- 2: Human-in-the-loop control of haptic devices: now and the future
- 3: TinyML: The Quest for Next-Generation Computing
- 4: Advancement in manufacturing and sustainability
- 5: Sensors of Things





IMPORTANT DATES

REGULAR PAPERS DEADLINE:

In order to accommodate several extensions requests the Organizing Commette is pleased to announce a new deadline

May 15th, 2022



TUTORIAL DEADLINE: May 13th ,2022 **NOTIFICATION REGULAR PAPERS:** June 1st. 2022 **NOTIFICATION TUTORIALS:** May 31th, 2022 **CAMERA READY DEADLINE:** July 1st, 2022

SUBMIT YOUR WORK

The International Scientific Committee invites authors to submit high quality manuscripts using the Springer Proceedings paper template. The number of pages of the manuscripts must be between 6 (minimum) and 10 (maximum). All accepted papers will be published in Lecture Notes in Networks and Systems. https://www.springer.com/series/15179

Conference Proceedings will be indexed by Scopus and ISI Web of Science. Authors of selected papers will be invited to submit an extended version of their contributions in special issues of relevant scientific journals.



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